Lighting Color

• White

LNJ0S2F8BRA

Hight Bright Surface Mounting Chip LED

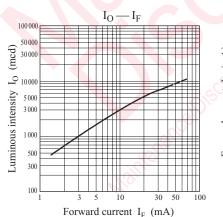
Strobe PCB Type

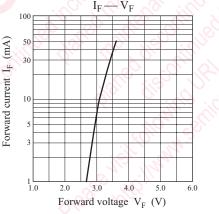
Absolute Maximum Ratings $T_a = 25^{\circ}C$

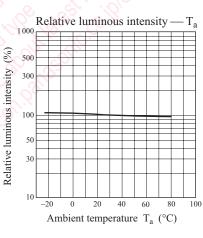
Parameter	Symbol	Rating	Unit
		120	
Power dissipation	P _D	120	mW
Forward current	I _F	30	mA
Pulse forward current	I _{FP}	60	mA
Reverse voltage	V _R	5	v
Operating ambient temperature	T _{opr}	-30 to +85	°C
Storage temperature	T _{stg}	-40 to +100	°C

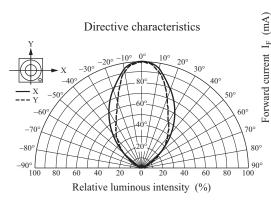
Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

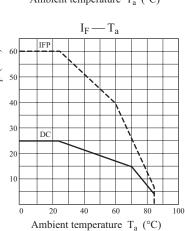
Reverse voltage	V _R	5 V				
Operating ambient temperature	T _{opr}	-30 to +85 °C				
Storage temperature	T _{stg}	-40 to +100 °C				
Electro-Optical Characteristics T _a	= 25°C±3°	c	tifecy	5		
				1		
Parameter	Symbol	Conditions	Min	Тур	Max	Uni
	Symbol	Conditions $I_F = 25 \text{ mA} / \text{chip}$	Min 4000	Typ 6 000	Max	
Luminous intensity					Max 10	mcc
Luminous intensity Reverse current	I _{O-25}	$I_F = 25 \text{ mA} / \text{chip}$				mcc
Parameter Luminous intensity Reverse current Forward voltage Chromaticity coordinates	I _{O-25} I _R	$I_F = 25 \text{ mA} / \text{chip}$ $V_R = 5 \text{ V} / \text{chip}$		6000	10	mcc μA







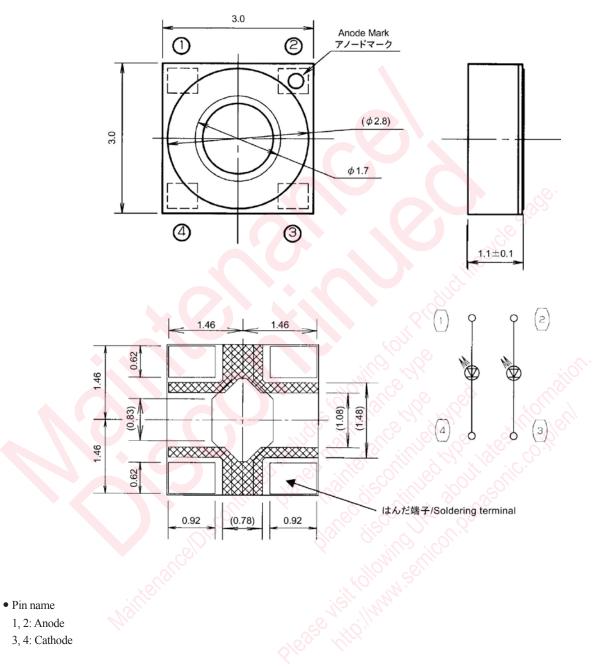




LNJ0S2F8BRA

Package (Unit: mm)

KLPFTR4KS200



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